METHOD OF MANUFACTURE AND IDENTIFICATION OF SEMICONDUCTOR CHIP MARKED FOR IDENTIFICATION WITH INTERNAL MARKING INDICIA AND PROTECTION THEREOF BY NON-BLACK LAYER AND DEVICE PRODUCED THEREBY

ABSTRACT OF THE DISCLOSURE

An electronic integrated circuit has a planar front surface and a planar back surface. Internal marking indicia identification are marked upon an marking surface on the exterior surface of the chip. The internal identification indicia on the chip surface are protected against remarking by a non-black, colored, optically-transmissive layer, so the indicia are visible through the optically-transmissive material. Electrical interconnection means connect to the electrical contact site through the package. There is least one electrical contact site on an exterior surface of the chip.

FIGURE 1 IS SUGGESTED FOR PUBLICATION